LESD5Z5.0C-H
ESD PROTECTION DIODE

Discription

The LESD5Z5.0C-H protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.
It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



SOD-523

Features

- ★ Transient protection for high-speed data lines
  IEC 61000-4-2(ESD) ±30kV (Contact)
  ±30kV (Air)
  IEC 61000-4-4(EFT) 40A (5/50 ns)
- ★ Peak power dissipation: 128W (8/20us)
- ★ Working voltages : 5V
- ★ Protects one Vcc or data line
- ★ Low clamping voltage
- ★ Low leakage current



Circuit Diagram

Ordering Information

Product ID	Pack	Qty(PCS)
LESD5Z5.0C-H	SOD-523	3000

Absolute Ratings(Tamb = 25°C)

Symbol	Parameter	Value	Units
P_{PP}	Peak Pulse Power (t_p = 8/20 μ s)	128	W
T_L	Maximum lead temperature for soldering during 10s	260	°C
T_{stg}	Storage Temperature Range	-55 to +155	°C
T_{op}	Operating Temperature Range	-40 to +125	°C
T_j	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD) air discharge contact discharge	±30 ±30	KV
	IEC61000-4-4 (EFT)	40	A

Electrical Characteristics

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V_{RWM}	Reverse Working Voltage				5.0	V
V_{BR}	Reverse Breakdown Voltage	I_T = 1mA	5.6		9.0	V
I_R	Reverse Leakage Current	V_{RWM} = 5.0V			0.1	μA
V_C	Clamping Voltage	I_{PP} = 5A, t_p = 8/20μs			11.6	V
		I_{PP} = 8A, t_p = 8/20μs			16	V
C_J	Junction Capacitance	V_R = 0V, f = 1MHz		10	15	pF

Typical Characteristics

Fig 1 8/20μs Waveform per IEC61000-4-5

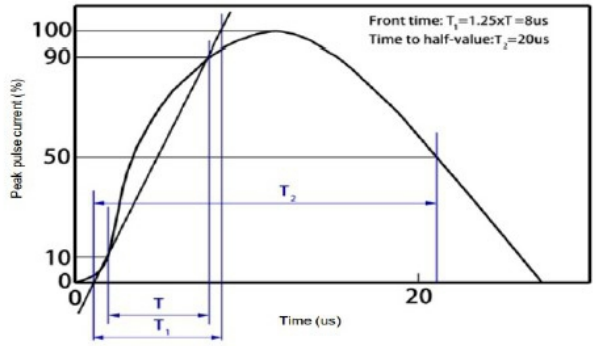


Fig 2 Contact Discharge Current Waveform per IEC 61000-4-2)

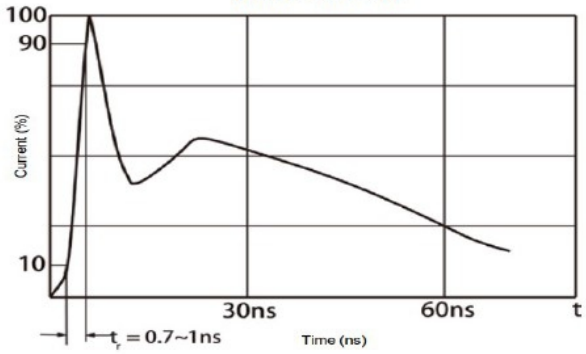


Fig 3 Power Derating Curve

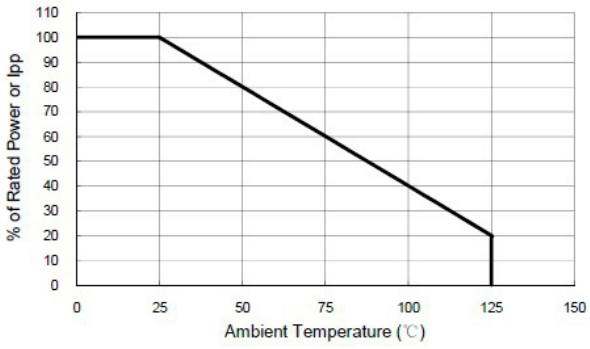


Fig 4 Voltage vs Capacitance

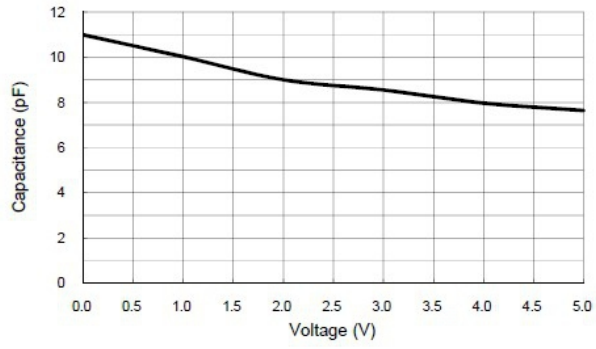


Fig 5 Voltage Sweeping

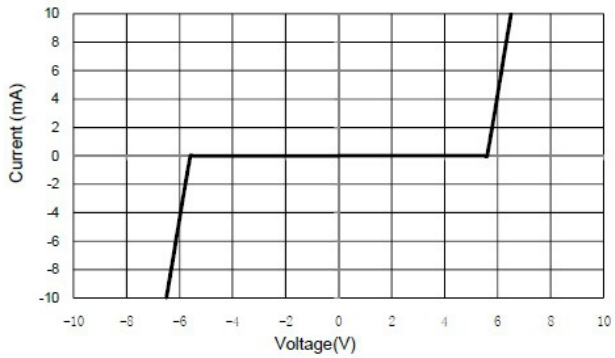
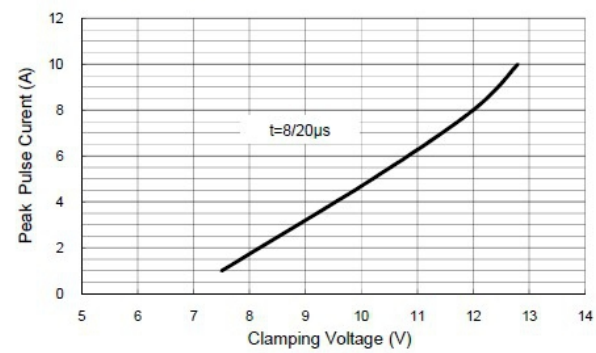
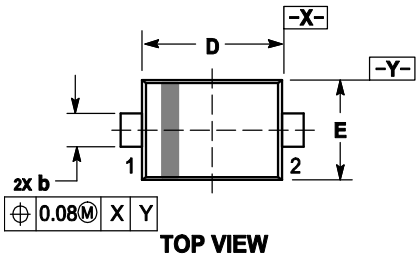


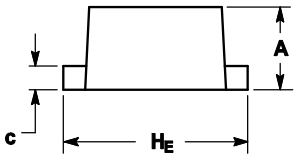
Fig 6 Clamping Voltage vs Peak Pulse Current



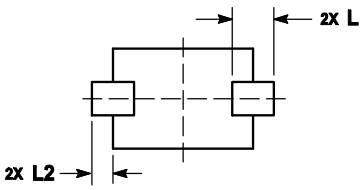
Outline And Dimensions



TOP VIEW



SIDE VIEW



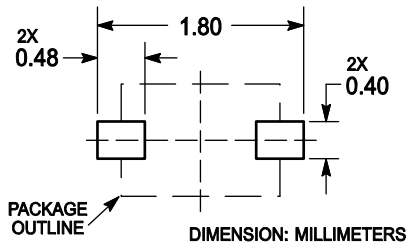
BOTTOM VIEW

Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.60	0.70	0.020	0.024	0.028
b	0.25	0.30	0.35	0.010	0.012	0.014
c	0.07	0.14	0.20	0.003	0.006	0.008
D	1.10	1.20	1.30	0.043	0.047	0.051
E	0.70	0.80	0.90	0.028	0.031	0.035
H_E	1.50	1.60	1.70	0.059	0.063	0.067
L	0.30 REF			0.012 REF		
L_2	0.15	0.20	0.25	0.006	0.008	0.010

Soledering Footprint



DIMENSION: MILLIMETERS

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